

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Jui-Pin Hung	08/30/2011
Jing-Cheng Lin	08/30/2011
Nai-Wei Liu	08/30/2011
Chin-Chuan Chang	08/30/2011
Chen-Hua Yu	09/05/2011
Shin-Puu Jeng	09/05/2011
Chin-Fu Kao	08/31/2011
Yi-Chao Mao	08/30/2011
Szu Wei Lu	08/30/2011

**RECEIVING PARTY DATA**

<b>Name:</b>	Taiwan Semiconductor Manufacturing Company, Ltd.
<b>Street Address:</b>	No. 8, Li-Hsin Rd. 6
<b>Internal Address:</b>	Science-Based Industrial Park
<b>City:</b>	Hsin-Chu
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77 R.O.C.

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	13228244

**CORRESPONDENCE DATA**

**Fax Number:** (972)732-9218  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
**Phone:** 972-732-1001  
**Email:** colgrove@slater-matsil.com  
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**Address Line 1:** 17950 Preston Road

**501652475**

**PATENT**  
**REEL: 026877 FRAME: 0793**

**CH \$40.00 13228244**

Address Line 2: Suite 1000  
Address Line 4: Dallas, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM11-0325
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NAME OF SUBMITTER:	Sherry L. Colgrove
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Total Attachments: 3 source=TSM11-0325_Assignment#page1.tif source=TSM11-0325_Assignment#page2.tif source=TSM11-0325_Assignment#page3.tif
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ATTORNEY DOCKET NO. TSM11-0325
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**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and





WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Packaging Methods and Structures Using a Die Attach Film			
SIGNATURE OF INVENTOR AND NAME	 Jui-Pin Hung	 Jing-Cheng Lin	 Nai-Wei Liu	 Chin-Chuan Chang
DATE	2011/8/30	2011/8/30	2011/8/30	2011.8.30
RESIDENCE (City, Country)	Hsin-Chu Taiwan, R.O.C.	Hsin-Chu Taiwan R.O.C.	Fengshan City Taiwan, R.O.C.	Zhudong Township Taiwan, R.O.C.

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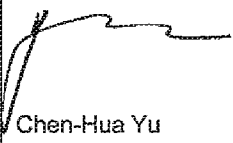

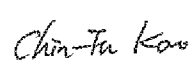
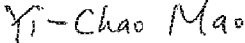
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<b>Packaging Methods and Structures Using a Die Attach Film</b>			
SIGNATURE OF INVENTOR AND NAME	 Chen-Hua Yu	 Shin-Puu Jeng	 Chin-Fu Kao	 Yi-Chao Mao
DATE	9/5/11	9/5/2011	2011/08/31	2011/8/30
RESIDENCE (City, Country)	Hsin-Chu Taiwan, R.O.C.	Hsin-Chu Taiwan, R.O.C.	Taipei City Taiwan, R.O.C.	Zhongli City Taiwan, R.O.C.

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WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof, and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Packaging Methods and Structures Using a Die Attach Film			
SIGNATURE OF INVENTOR AND NAME	<i>Szu-Wei Lu</i> Szu Wei Lu			
DATE	8/30 '11			
RESIDENCE (City, Country)	Hsin-Chu Taiwan, R.O.C.			